

Microelectronics International

Volume 29, Number 2, 2012

ISSN 1356-5362

Contents

- 70 Access this journal online
- 71 **Comparison approach on strain behavior of PBGA assembly by considering different thermal-mechanical compound loading modes**
Guangbin Tan, Ping Yang, Tianbo Li, Tao Xi, Xiaoming Yuan and Jianming Yang
- 76 **Power management of a wireless sensor node with solar energy harvesting technology**
Kah-Yoong Chan, Hee-Joe Phoon, Chee-Pun Ooi, Wai-Leong Pang and Sew-Kin Wong
- 83 **Characterization and modelling of miniature ferrite transformer for high frequency applications**
Mirjana S. Damnjanović, Ljiljana D. Živanov, Snezana M. Djurić, Andrea M. Marić, Aleksandar B. Menićanin, Goran J. Radosavljević and Nelu V. Blaž
- 90 **An 11 GHz low-phase-noise voltage-controlled oscillator**
Mei-Ling Yeh, Yao-Chian Lin and Wei-Chieh Chang
- 96 **Fabrication of porous ZnO thin films using wet chemical etching with 0.5% HNO₃**
Ang Chai Im, Leonard Lu Tze Jian, Ooi Poh Kok, Suriani Yaakob, Ching Chin Guan, Ng Sha Shiong, Zainuriah Hassan, Haslan Abu Hassan and Mat Johar Abdullah
- 101 **Optimal placement of modules on partially reconfigurable device for reconfiguration time improvement**
Bouraoui Ouni and Abdellatif Mtibaa
- 108 **The bulk alloy microstructure and tensile properties of Sn-1Ag-0.5Cu-xAl lead-free solder alloys (x= 0, 1, 1.5 and 2 wt.%)**
Dhafer Abdul-Ameer Shmawah, Mohd Faizul Mohd Sabri, Irfan Anjum Badruddin and Fa Xing Che
- 117 **Industry news**
- 121 **New products**
- 124 **Exhibitions and conferences**
- 128 **International diary**

C O P E COMMITTEE ON PUBLICATION ETHICS

This journal is a member of and subscribes to the principles of the Committee on Publication Ethics